

### FEATURES

- 10µs Short Circuit Withstand
- High Thermal Cycling Capability
- Soft Punch Through Silicon
- Isolated AISiC Base With AlN Substrates
- Lead Free Construction

### APPLICATIONS

- High Reliability Inverters
- Motor Controllers
- Traction Drives
- Choppers

The Powerline range of high power modules includes half bridge, chopper, dual, single and bi-directional switch configurations covering voltages from 1200V to 6500V and currents up to 2400A.

The DIM1200ESM33-F000 is a single switch 3300V, n-channel enhancement mode, insulated gate bipolar transistor (IGBT) module. The IGBT has a wide reverse bias safe operating area (RBSOA) plus 10µs short circuit withstand. This device is optimised for traction drives and other applications requiring high thermal cycling capability.

The module incorporates an electrically isolated base plate and low inductance construction enabling circuit designers to optimise circuit layouts and utilise grounded heat sinks for safety.

### ORDERING INFORMATION

Order As:

### DIM1200ESM33-F000

Note: When ordering, please use the complete part number

### KEY PARAMETERS

$V_{CES}$	<b>3300V</b>
$V_{CE(sat)}$ * (typ)	<b>2.8V</b>
$I_C$ (max)	<b>1200A</b>
$I_{C(PK)}$ (max)	<b>2400A</b>

\* Measured at the auxiliary terminals

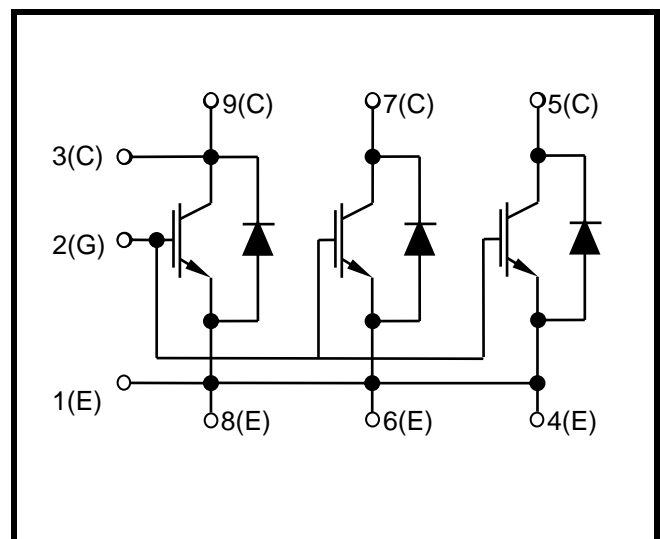
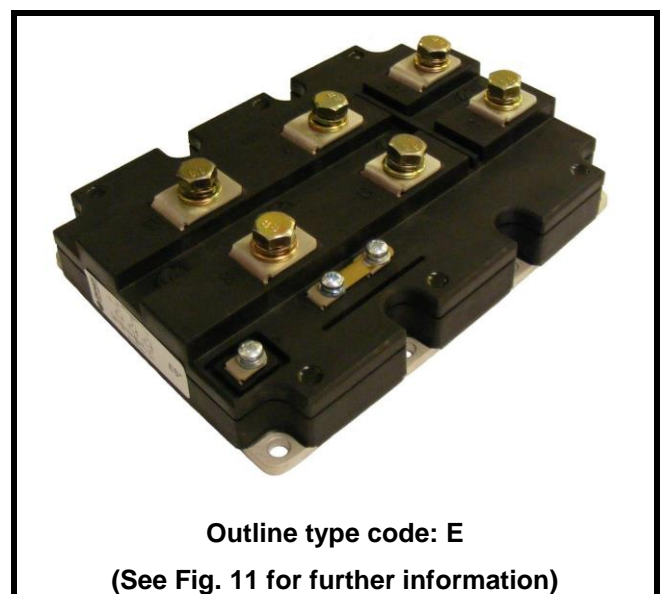


Fig. 1 Circuit configuration



Outline type code: E

(See Fig. 11 for further information)

Fig. 2 Package

## ABSOLUTE MAXIMUM RATINGS

Stresses above those listed under 'Absolute Maximum Ratings' may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed. Exposure to Absolute Maximum Ratings may affect device reliability.

$T_{case} = 25^{\circ}\text{C}$  unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
$V_{CES}$	Collector-emitter voltage	$V_{GE} = 0V$	3300	V
$V_{GES}$	Gate-emitter voltage		$\pm 20$	V
$I_C$	Continuous collector current	$T_{case} = 90^{\circ}\text{C}$	1200	A
$I_{C(PK)}$	Peak collector current	1ms, $T_{case} = 115^{\circ}\text{C}$	2400	A
$P_{max}$	Max. transistor power dissipation	$T_{case} = 25^{\circ}\text{C}$ , $T_j = 150^{\circ}\text{C}$	15.6	kW
$I^2t$	Diode $I^2t$ value	$V_R = 0$ , $t_p = 10\text{ms}$ , $T_j = 125^{\circ}\text{C}$	720	$\text{kA}^2\text{s}$
$V_{isol}$	Isolation voltage – per module	Commoned terminals to base plate. AC RMS, 1 min, 50Hz	6000	V
$Q_{PD}$	Partial discharge – per module	IEC1287, $V_1 = 3500V$ , $V_2 = 2600V$ , 50Hz RMS	10	pC

## THERMAL AND MECHANICAL RATINGS

Internal insulation material:	AlN
Baseplate material:	AlSiC
Creepage distance:	33mm
Clearance:	20mm
CTI (Comparative Tracking Index):	>600

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Units
$R_{th(j-c)}$	Thermal resistance – transistor	Continuous dissipation - junction to case	-	-	8	$^{\circ}\text{C}/\text{kW}$
$R_{th(j-c)}$	Thermal resistance – diode	Continuous dissipation - junction to case	-	-	16	$^{\circ}\text{C}/\text{kW}$
$R_{th(c-h)}$	Thermal resistance – case to heatsink (per module)	Mounting torque 5Nm (with mounting grease)	-	-	6	$^{\circ}\text{C}/\text{kW}$
$T_j$	Junction temperature	Transistor	-	-	150	$^{\circ}\text{C}$
		Diode	-	-	125	$^{\circ}\text{C}$
$T_{stg}$	Storage temperature range	-	-40	-	125	$^{\circ}\text{C}$
	Screw torque	Mounting – M6	-	-	5	Nm
		Electrical connections – M4	-	-	2	Nm
		Electrical connections – M8	-	-	10	Nm

**ELECTRICAL CHARACTERISTICS**
**T<sub>case</sub> = 25°C unless stated otherwise.**

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
I <sub>CES</sub>	Collector cut-off current	V <sub>GE</sub> = 0V, V <sub>CE</sub> = V <sub>CES</sub>			5	mA
		V <sub>GE</sub> = 0V, V <sub>CE</sub> = V <sub>CES</sub> , T <sub>case</sub> = 125°C			90	mA
I <sub>GES</sub>	Gate leakage current	V <sub>GE</sub> = ± 20V, V <sub>CE</sub> = 0V			1	μA
V <sub>GE(TH)</sub>	Gate threshold voltage	I <sub>C</sub> = 120mA, V <sub>GE</sub> = V <sub>CE</sub>	5.5	6.5	7.0	V
V <sub>CE(sat)</sub> <sup>†</sup>	Collector-emitter saturation voltage	V <sub>GE</sub> = 15V, I <sub>C</sub> = 1200A		2.8		V
		V <sub>GE</sub> = 15V, I <sub>C</sub> = 1200A, T <sub>j</sub> = 125°C		3.6		V
I <sub>F</sub>	Diode forward current	DC		1200		A
I <sub>FM</sub>	Diode maximum forward current	t <sub>p</sub> = 1ms		2400		A
V <sub>F</sub> <sup>†</sup>	Diode forward voltage	I <sub>F</sub> = 1200A		2.9		V
		I <sub>F</sub> = 1200A, T <sub>j</sub> = 125°C		3.0		V
C <sub>ies</sub>	Input capacitance	V <sub>CE</sub> = 25V, V <sub>GE</sub> = 0V, f = 1MHz		216		nF
Q <sub>g</sub>	Gate charge	±15V		30		μC
C <sub>res</sub>	Reverse transfer capacitance	V <sub>CE</sub> = 25V, V <sub>GE</sub> = 0V, f = 1MHz		3.3		nF
L <sub>M</sub>	Module inductance			10		nH
R <sub>INT</sub>	Internal transistor resistance			90		μΩ
SC <sub>Data</sub>	Short circuit current, I <sub>SC</sub>	T <sub>j</sub> = 125°C, V <sub>CC</sub> = 2500V t <sub>p</sub> ≤ 10μs, V <sub>GE</sub> ≤ 15V V <sub>CE(max)</sub> = V <sub>CES</sub> - L* x dl/dt IEC 60747-9		5500		A

**Note:**
<sup>†</sup> Measured at the power busbars, not the auxiliary terminals

<sup>\*</sup> L is the circuit inductance + L<sub>M</sub>

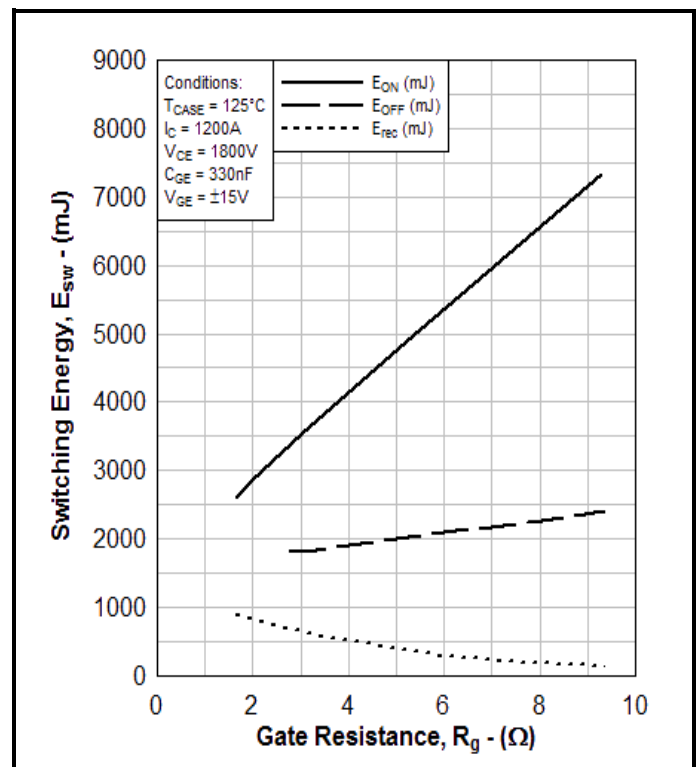
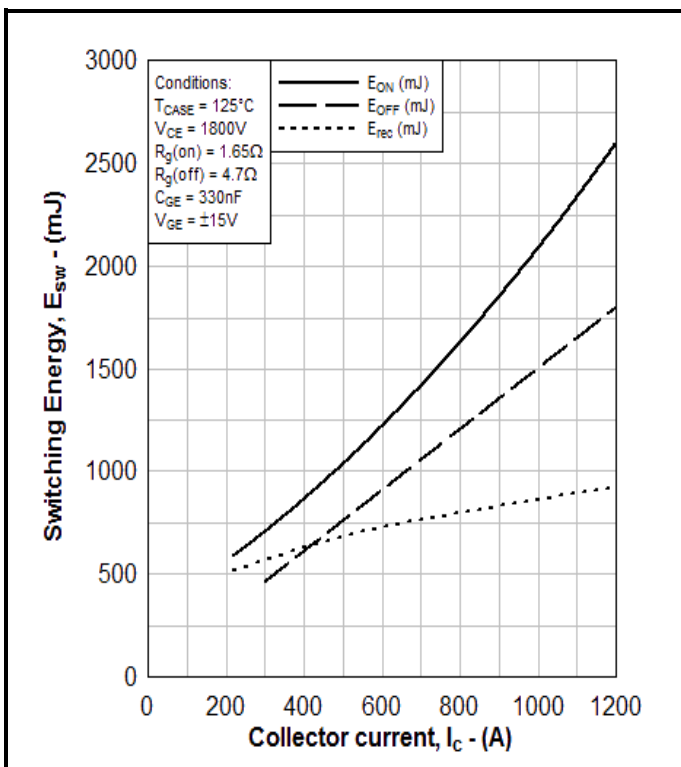
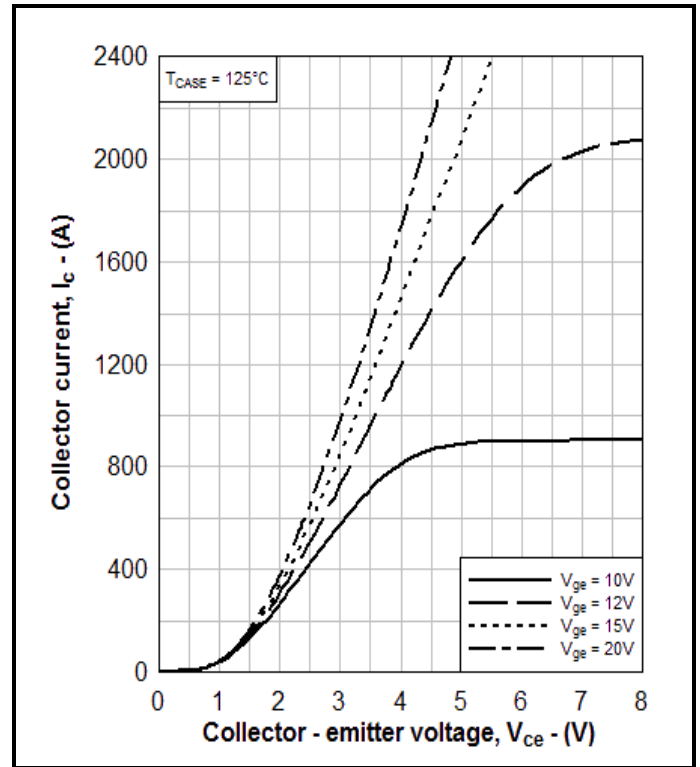
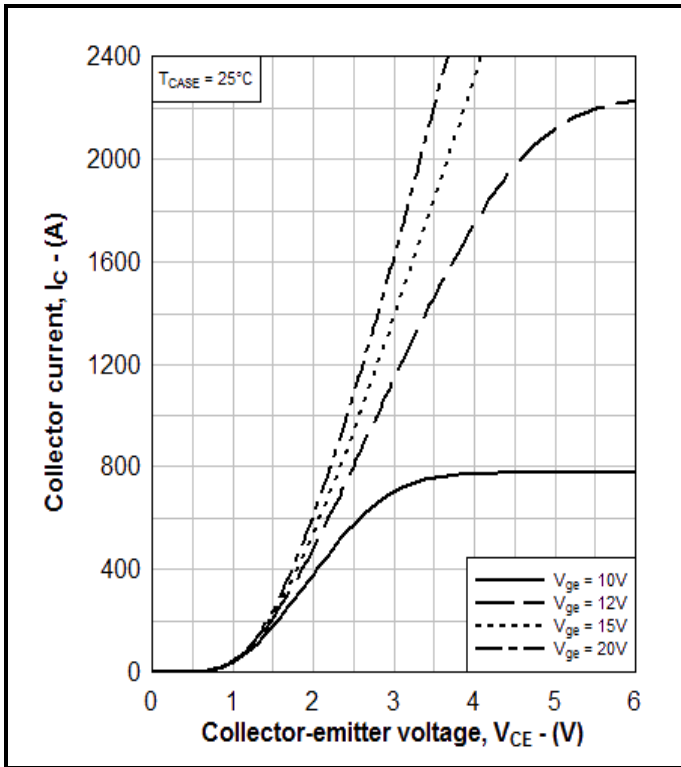
## ELECTRICAL CHARACTERISTICS

$T_{\text{case}} = 25^{\circ}\text{C}$  unless stated otherwise

Symbol	Parameter	Test Conditions		Min	Typ.	Max	Units
$t_{d(\text{off})}$	Turn-off delay time	$I_C = 1200\text{A}$ $V_{GE} = \pm 15\text{V}$ $V_{CE} = 1800\text{V}$ $C_{ge} = 330\text{nF}$ $L_S \sim 100\text{nH}$	$R_{G(\text{ON})} = 2.7\Omega$ $R_{G(\text{OFF})} = 4.7\Omega$		2150		ns
$t_f$	Fall time				230		ns
$E_{\text{OFF}}$	Turn-off energy loss				1550		mJ
$t_{d(\text{on})}$	Turn-on delay time				1300		ns
$t_r$	Rise time				275		ns
$E_{\text{ON}}$	Turn-on energy loss		$R_{G(\text{ON})} = 1.65\Omega$ $R_{G(\text{OFF})} = 4.7\Omega$	1850		mJ	
$Q_{rr}$	Diode reverse recovery charge	$I_F = 2400\text{A}$ $V_{CE} = 1800\text{V}$ $dI_F/dt = 6000\text{A}/\mu\text{s}$			480		$\mu\text{C}$
$I_{rr}$	Diode reverse recovery current			1000		A	
$E_{\text{rec}}$	Diode reverse recovery energy			450		mJ	

$T_{\text{case}} = 125^{\circ}\text{C}$  unless stated otherwise

Symbol	Parameter	Test Conditions		Min	Typ.	Max	Units
$t_{d(\text{off})}$	Turn-off delay time	$I_C = 1200\text{A}$ $V_{GE} = \pm 15\text{V}$ $V_{CE} = 1800\text{V}$ $C_{ge} = 330\text{nF}$ $L_S \sim 100\text{nH}$	$R_{G(\text{ON})} = 2.7\Omega$ $R_{G(\text{OFF})} = 4.7\Omega$		2200		ns
$t_f$	Fall time				240		ns
$E_{\text{OFF}}$	Turn-off energy loss				1800		mJ
$t_{d(\text{on})}$	Turn-on delay time				1200		ns
$t_r$	Rise time				315		ns
$E_{\text{ON}}$	Turn-on energy loss		$R_{G(\text{ON})} = 1.65\Omega$ $R_{G(\text{OFF})} = 4.7\Omega$	2600		mJ	
$Q_{rr}$	Diode reverse recovery charge	$I_F = 1200\text{A}$ $V_{CE} = 1800\text{V}$ $dI_F/dt = 6000\text{A}/\mu\text{s}$			900		$\mu\text{C}$
$I_{rr}$	Diode reverse recovery current			1200		A	
$E_{\text{rec}}$	Diode reverse recovery energy			900		mJ	



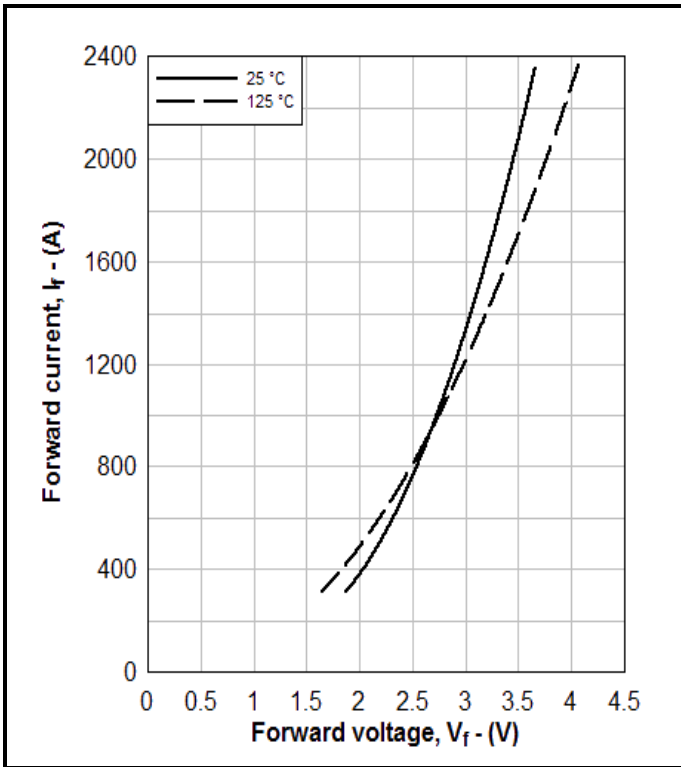


Fig. 7 Diode typical forward characteristics

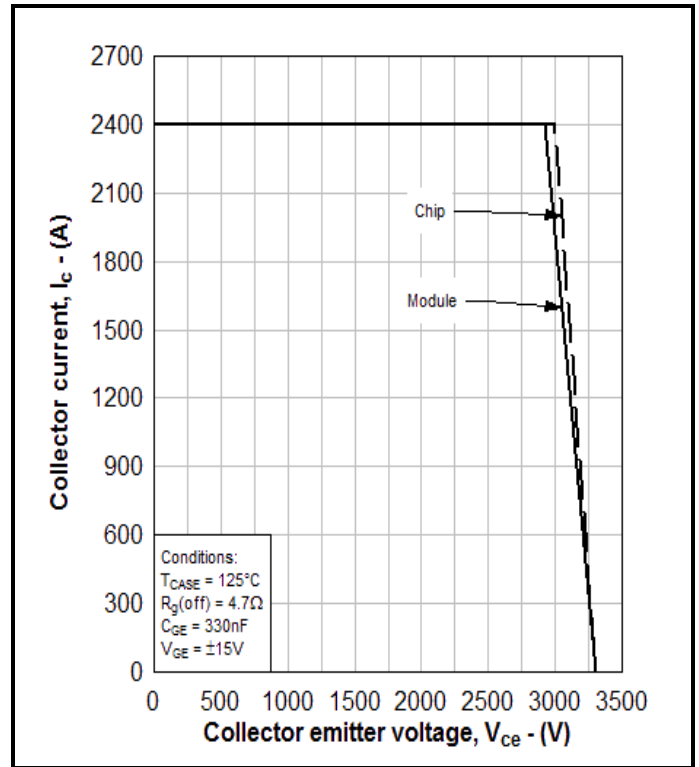


Fig. 8 Reverse bias safe operating area

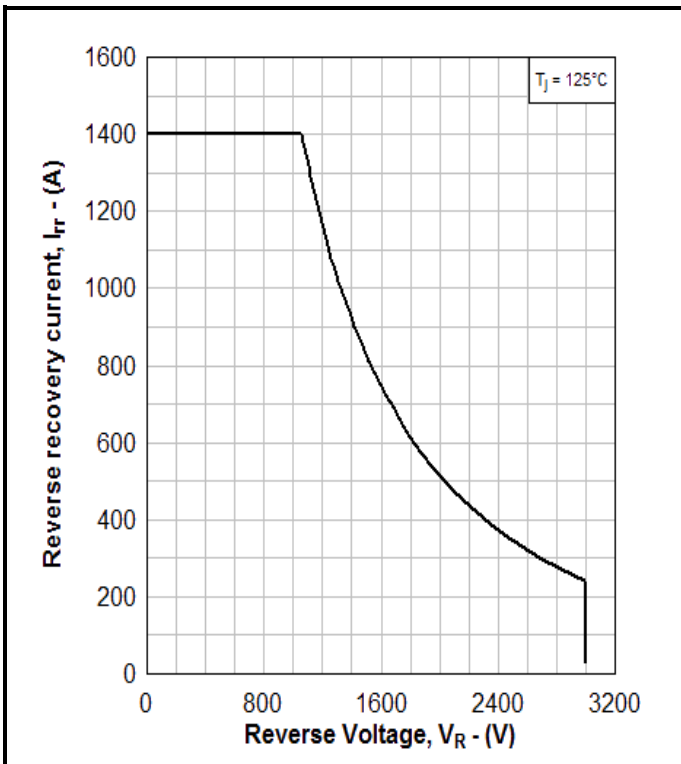


Fig. 9 Diode reverse bias safe operating area

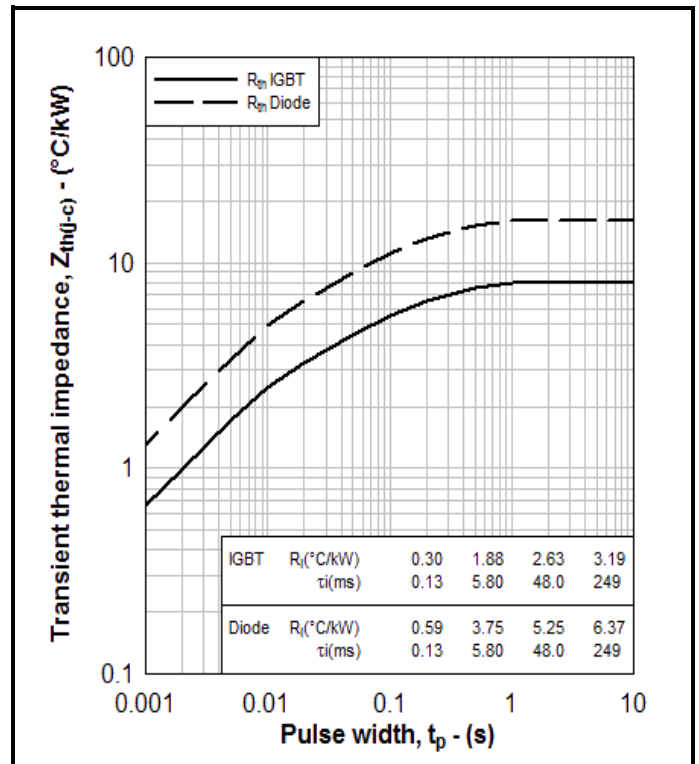
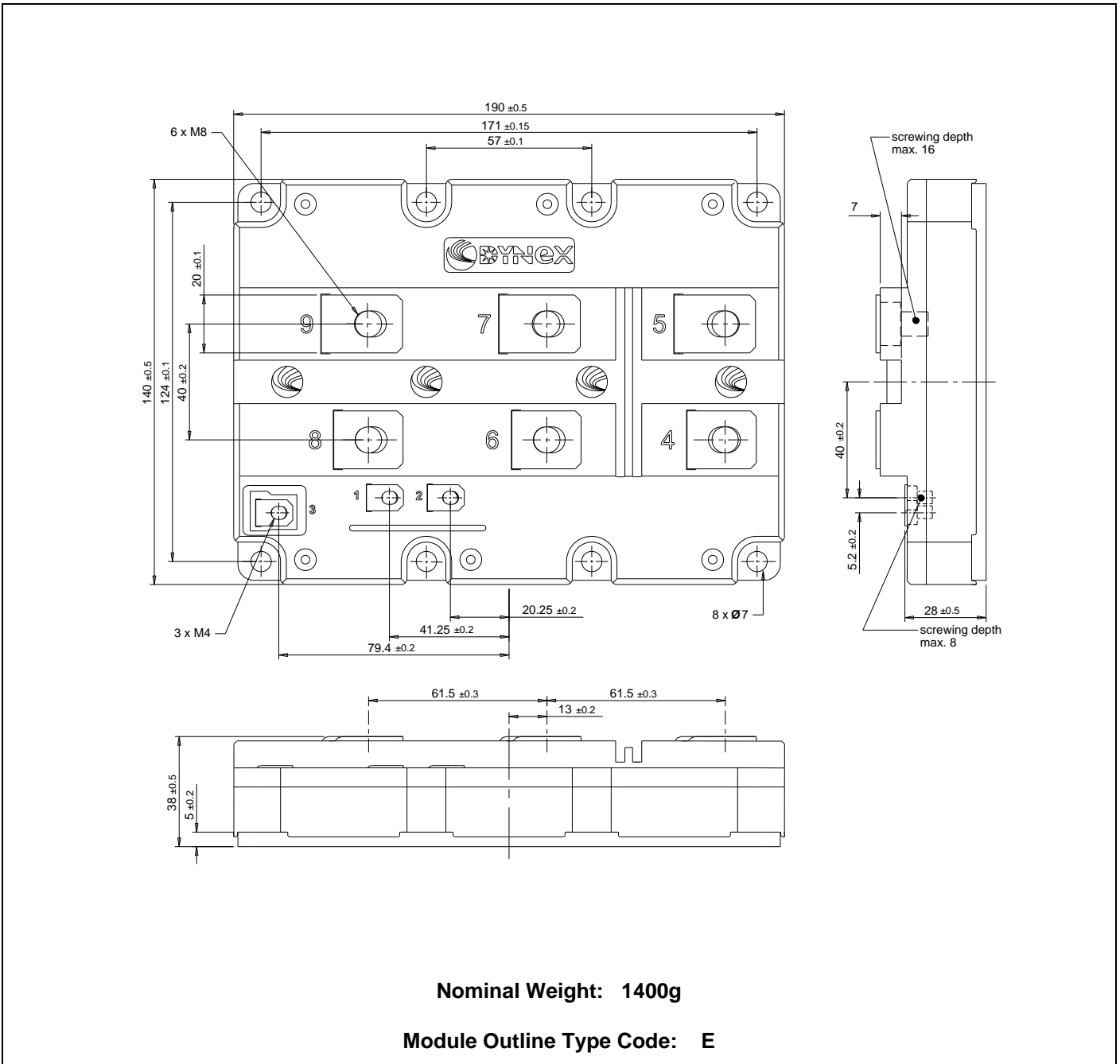


Fig. 10 Transient thermal impedance

**PACKAGE DETAILS**

For further package information, please visit our website or contact Customer Services.  
 All dimensions in mm, unless stated otherwise.  
**DO NOT SCALE.**



**Fig. 11 Module outline drawing**

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